



# STSJ50NH3LL

N-channel 30 V - 0.008  $\Omega$  - 12 A - PowerSO-8™  
ultra low gate charge STripFET™ Power MOSFET

## Features

Type	V <sub>DSS</sub>	R <sub>DS(on)</sub> (max)	I <sub>D</sub>
STSJ50NH3LL	30V	< 0.0105 $\Omega$	12A <sup>(1)</sup>

- Optimal R<sub>DS(on)</sub> x Q<sub>g</sub> trade-off @ 4.5V
- Reduced switching losses
- Reduced conduction losses
- Improved junction-case thermal resistance

## Applications

- Switching application

## Description

This series utilizes the latest advanced design rules of ST's proprietary STripFET™ technology, and a proprietary process for integrating a monolithic Scottky diode. The new Power MOSFET is optimized for the most demanding synchronous switch function in DC-DC converter for computer and telecom.

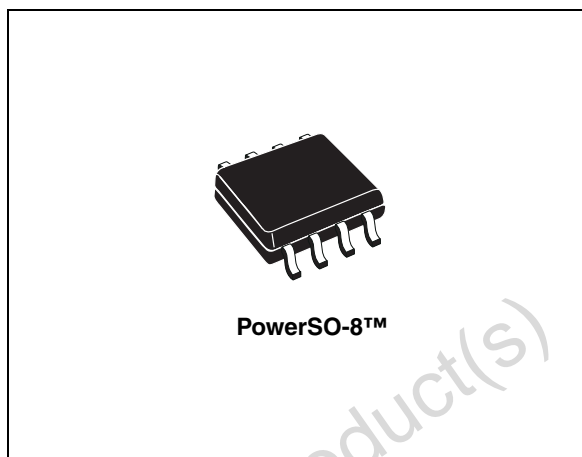


Figure 1. Internal schematic diagram

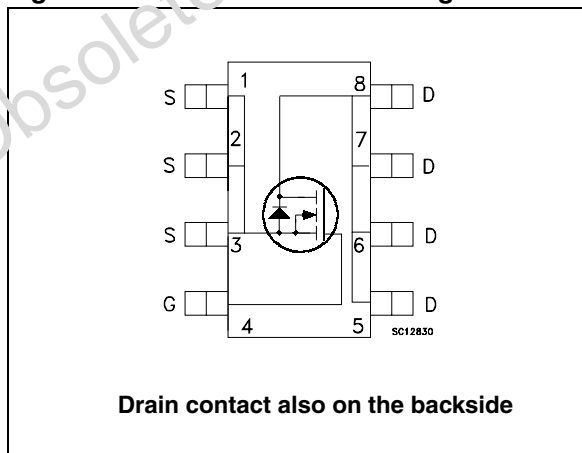


Table 1. Device summary

Order code	Marking	Package	Packaging
STSJ50NH3LL	50H3LL-	PowerSO-8	Tape & reel

Contents

1      **Electrical ratings** ..... 3

2      **Electrical characteristics** ..... 4

      2.1    Electrical characteristics (curves) ..... 6

3      **Test circuit** ..... 9

4      **Package mechanical data** ..... 10

5      **Revision history** ..... 12

Obsolete Product(s) - Obsolete Product(s)

# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage ( $V_{GS} = 0$ )	30	V
$V_{GS}^{(1)}$	Gate-source voltage	$\pm 16$	V
$V_{GS}^{(2)}$	Gate-source voltage	$\pm 18$	V
$I_D^{(4)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	50	A
$I_D^{(3)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	12	A
$I_D^{(4)}$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	31.3	A
$I_D^{(3)}$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	7.5	A
$I_{DM}^{(5)}$	Drain current (pulsed)	48	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$ <sup>(3)</sup>	3	W
	Total dissipation at $T_C = 25^\circ\text{C}$ <sup>(4)</sup>	50	W
$T_J$	Operating junction temperature	-55 to 150	$^\circ\text{C}$
$T_{stg}$	Storage temperature		

1. Continuous mode
2. Guaranteed for test time  $\leq 15\text{ms}$
3. This value is rated accordingly to  $R_{thj-pcb}$
4. This value is rated accordingly to  $R_{thj-c}$
5. Pulse width limited by safe operating area

**Table 3. Thermal resistance**

Symbol	Parameter	Value	Unit
$R_{thj-c}$	Thermal resistance junction-case Max	2.5	$^\circ\text{C/W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb Max	42	$^\circ\text{C/W}$

1. When mounted on 1 inch<sup>2</sup> FR-4 board, 2oz Cu ( $t < 10\text{sec.}$ )

**Table 4. Avalanche data**

Symbol	Parameter	Value	Unit
$I_{AV}$	Not repetitive avalanche current	7.5	A
$E_{AS}$	Single pulse avalanche energy (starting $T_J = 25^\circ\text{C}$ , $I_D = 7.5\text{ A}$ )	150	mJ

## 2 Electrical characteristics

( $T_{CASE}=25^{\circ}\text{C}$  unless otherwise specified)

**Table 5. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250\ \mu\text{A}$ , $V_{GS} = 0$	30			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating}$ $T_C=125^{\circ}\text{C}$			1 10	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 16\ \text{V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\ \mu\text{A}$	1			V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\ \text{V}$ , $I_D = 6\ \text{A}$ $V_{GS} = 4.5\ \text{V}$ , $I_D = 6\ \text{A}$		0.008 0.010	0.0105 0.013	$\Omega$ $\Omega$
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\ \text{V}$ , $I_D = 6\ \text{A}$ @ $125^{\circ}\text{C}$ $V_{GS} = 4.5\ \text{V}$ , $I_D = 6\ \text{A}$ @ $125^{\circ}\text{C}$		0.012 0.016		$\Omega$ $\Omega$

**Table 6. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$g_{fs}^{(1)}$	Forward transconductance	$V_{DS} = 10\ \text{V}$ , $I_D = 12\ \text{A}$		38		S
$C_{iss}$ $C_{oss}$ $C_{rss}$	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25\ \text{V}$ , $f = 1\ \text{MHz}$ , $V_{GS} = 0$		965 285 38		pF pF pF
$Q_g$ $Q_{gs}$ $Q_{gd}$	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 15\ \text{V}$ , $I_D = 12\ \text{A}$ $V_{GS} = 4.5\ \text{V}$ , (see Figure 16)		9 3.7 3	12	nC nC nC
$R_G$	Gate input resistance	$f = 1\ \text{MHz}$ Gate DC Bias = 0 Test signal level = 20 mV open drain	0.5	1.5	2.5	$\Omega$

1. Pulsed: pulse duration=300 $\mu\text{s}$ , duty cycle 1.5%

**Table 7. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$	Turn-on delay time Rise time	$V_{DD}=15\text{ V}$ , $I_D=6\text{ A}$ , $R_G=4.7\ \Omega$ , $V_{GS}=4.5\text{ V}$ (see Figure 15)		15 32		ns ns
$t_{d(off)}$ $t_f$	Turn-off delay time Fall time	$V_{DD}=15\text{ V}$ , $I_D=6\text{ A}$ , $R_G=4.7\ \Omega$ , $V_{GS}=4.5\text{ V}$ (see Figure 15)		18 8.5		ns ns

**Table 8. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$ $I_{SDM}^{(1)}$	Source-drain current Source-drain current (pulsed)				12 48	A A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD}=12\text{ A}$ , $V_{GS}=0$			1.3	V
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD}=12\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD}=20\text{ V}$ , $T_j=150\text{ }^\circ\text{C}$ (see Figure 20)		24 17.4 1.45		ns nC A

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration=300 $\mu\text{s}$ , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

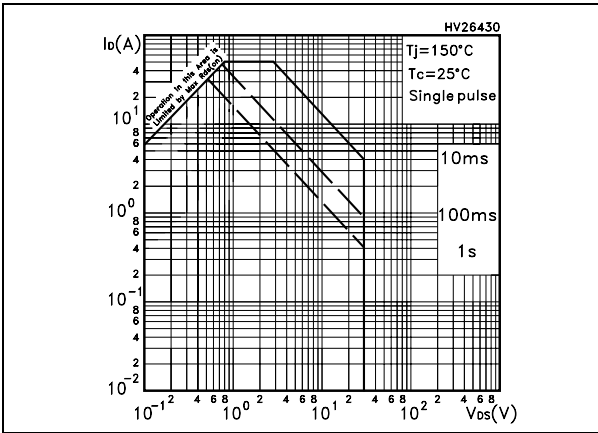


Figure 3. Thermal impedance

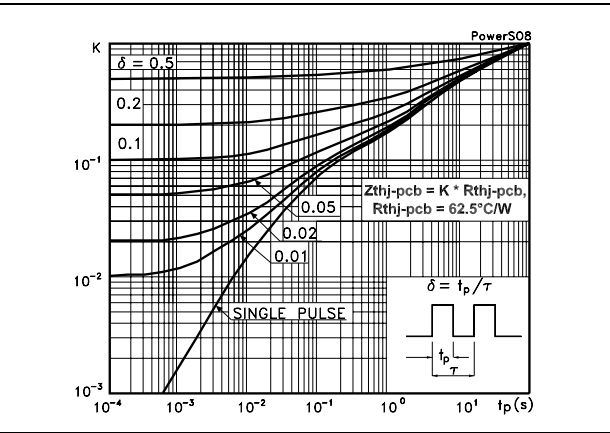


Figure 4. Output characteristics

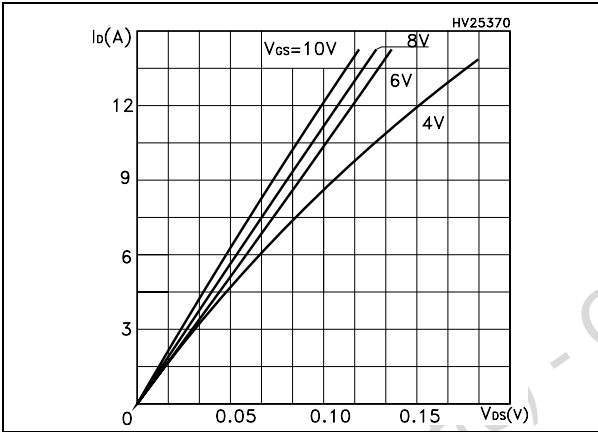


Figure 5. Transfer characteristics

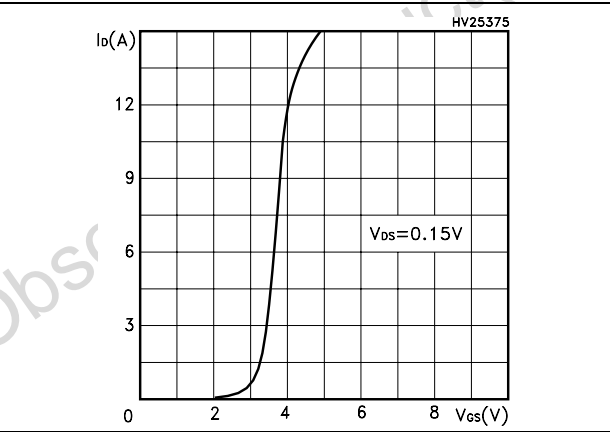


Figure 6. Transconductance

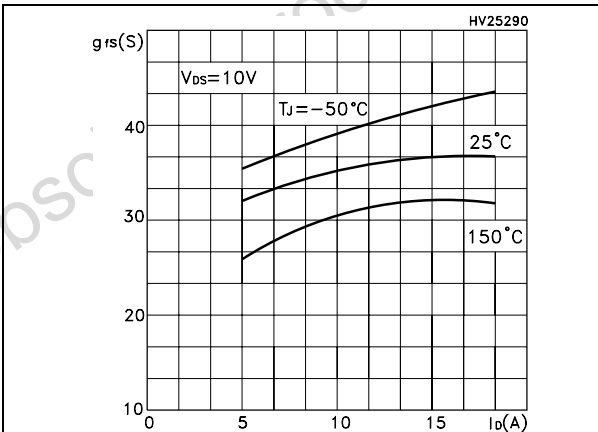


Figure 7. Static drain-source on resistance

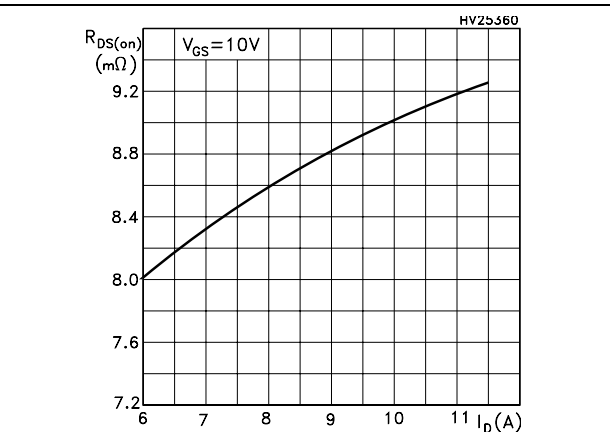


Figure 8. Gate charge vs gate-source voltage      Figure 9. Capacitance variations

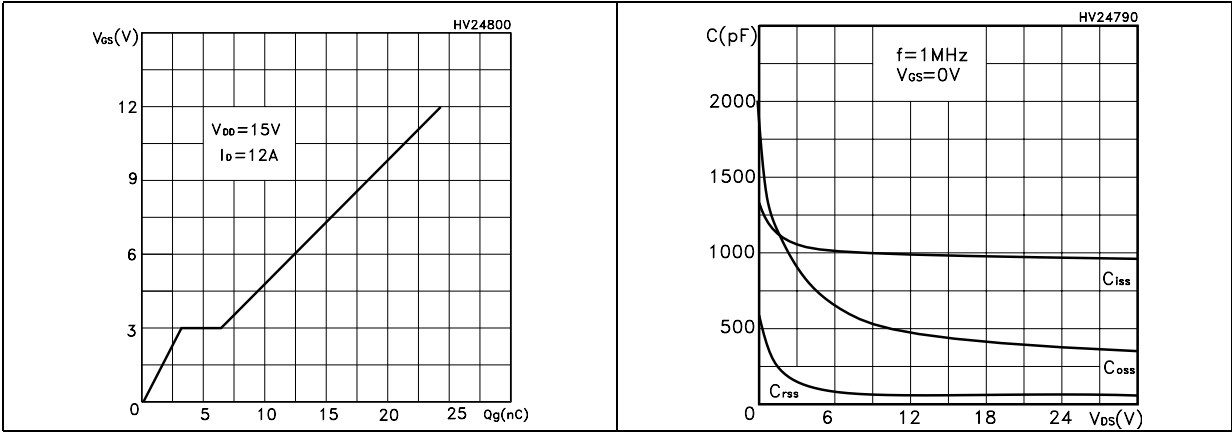


Figure 10. Normalized gate threshold voltage vs temperature      Figure 11. Normalized on resistance vs temperature

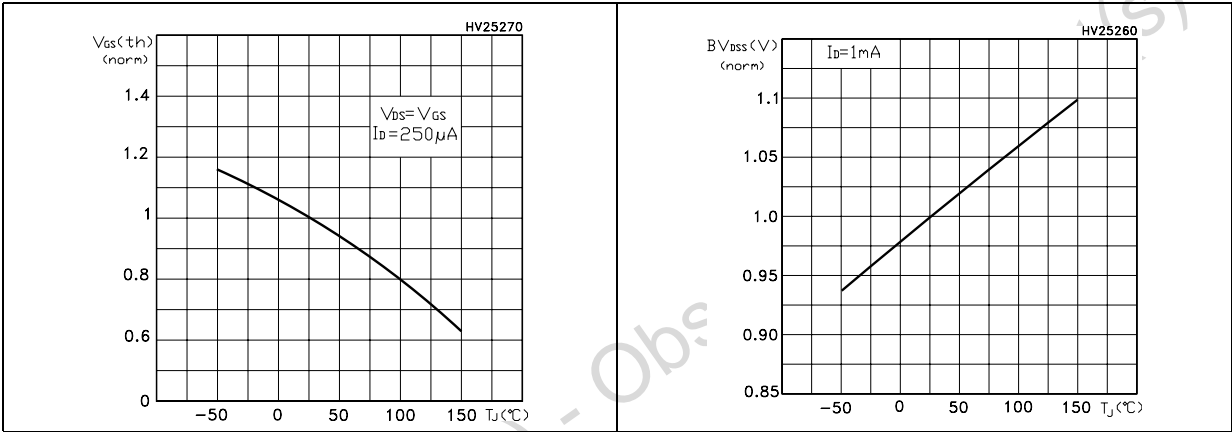


Figure 12. Source-drain diode forward characteristics      Figure 13. Normalized  $B_{V_{DS}}$  vs temperature

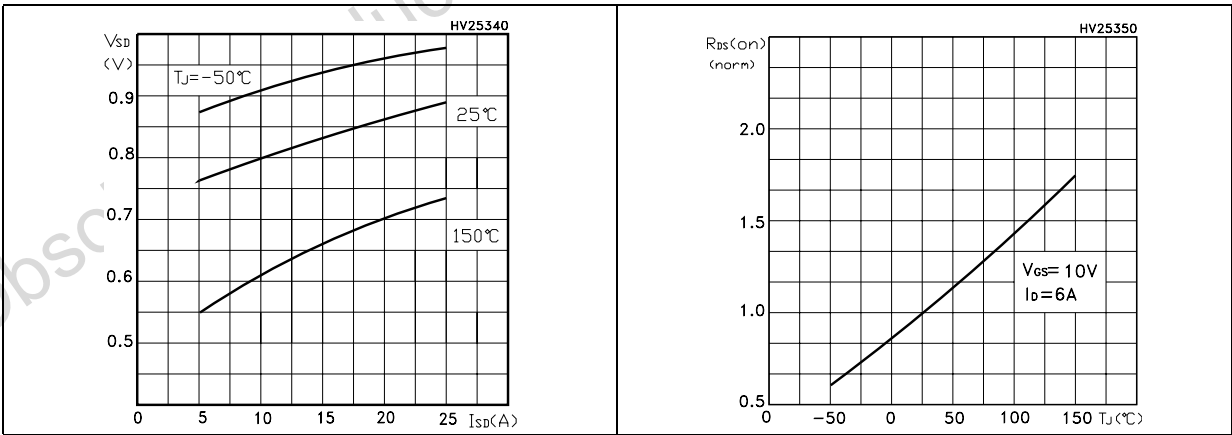
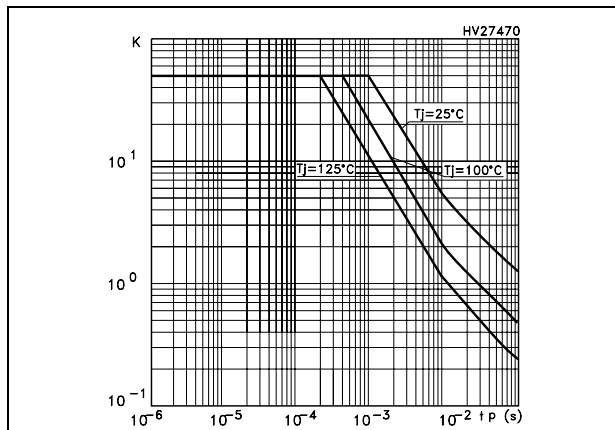


Figure 14. Allowable  $I_{AV}$  vs time in avalanche

The previous curve gives the single pulse safe operating area for unclamped inductive loads under the following conditions:

$$P_{D(AVE)} = 0.5 \cdot (1.3 \cdot BV_{DSS} \cdot I_{AV})$$

$$EAS_{(AR)} = P_{D(AVE)} \cdot t_{AV}$$

Where:

$I_{AV}$  is the allowable current in avalanche

$P_{D(AVE)}$  is the average power dissipation in avalanche (single pulse)

$t_{av}$  is the time in avalanche



### 3 Test circuit

Figure 15. Switching times test circuit for resistive load

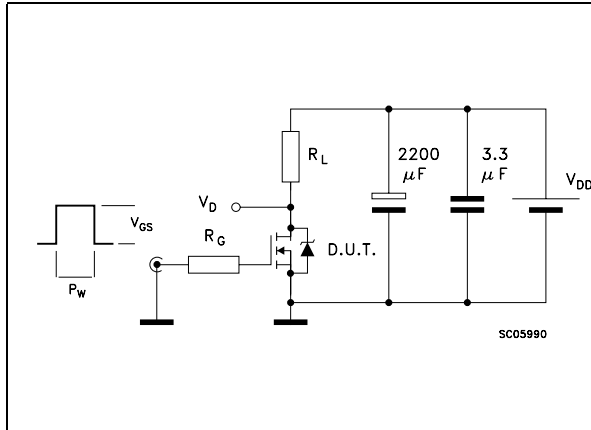


Figure 16. Gate charge test circuit

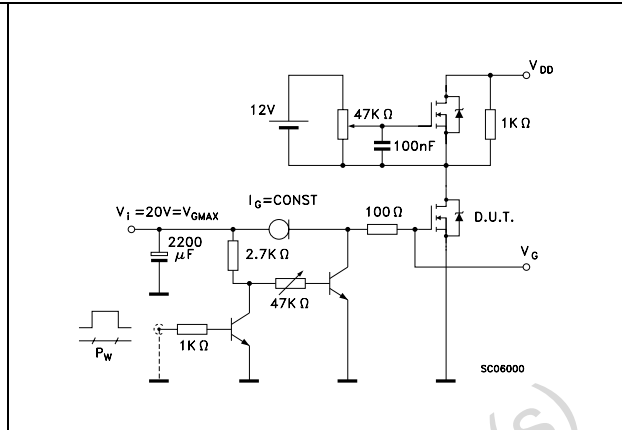


Figure 17. Test circuit for inductive load switching and diode recovery times

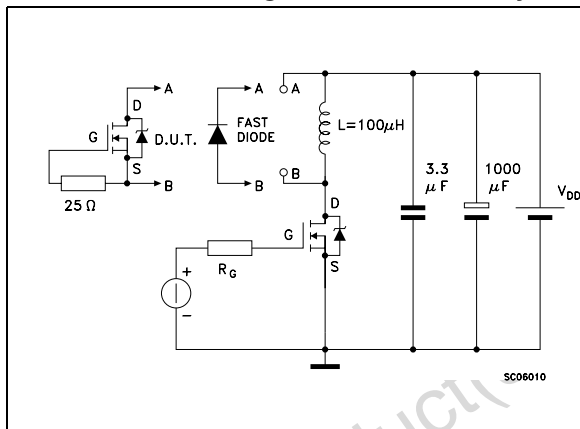


Figure 18. Unclamped inductive load test circuit

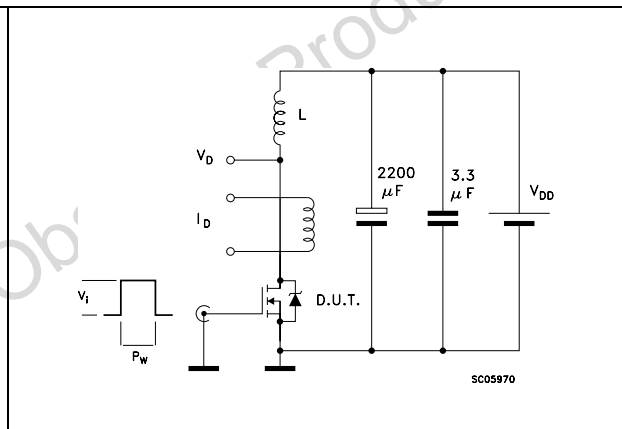


Figure 19. Unclamped inductive waveform

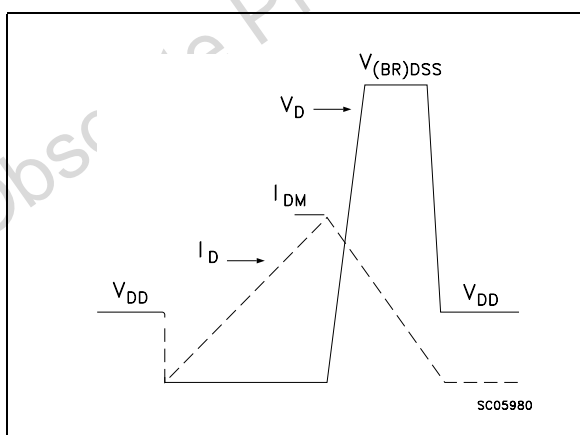
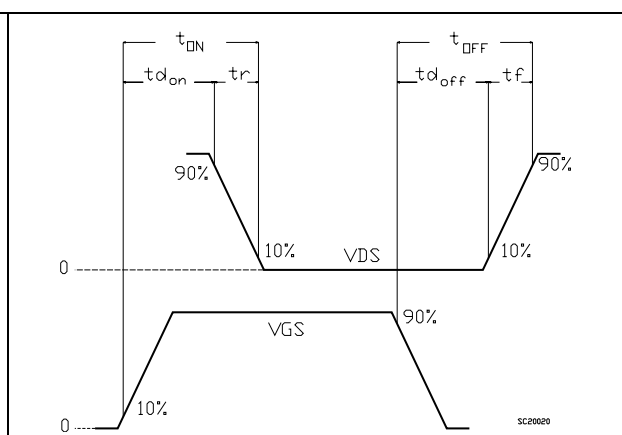


Figure 20. Switching time waveform



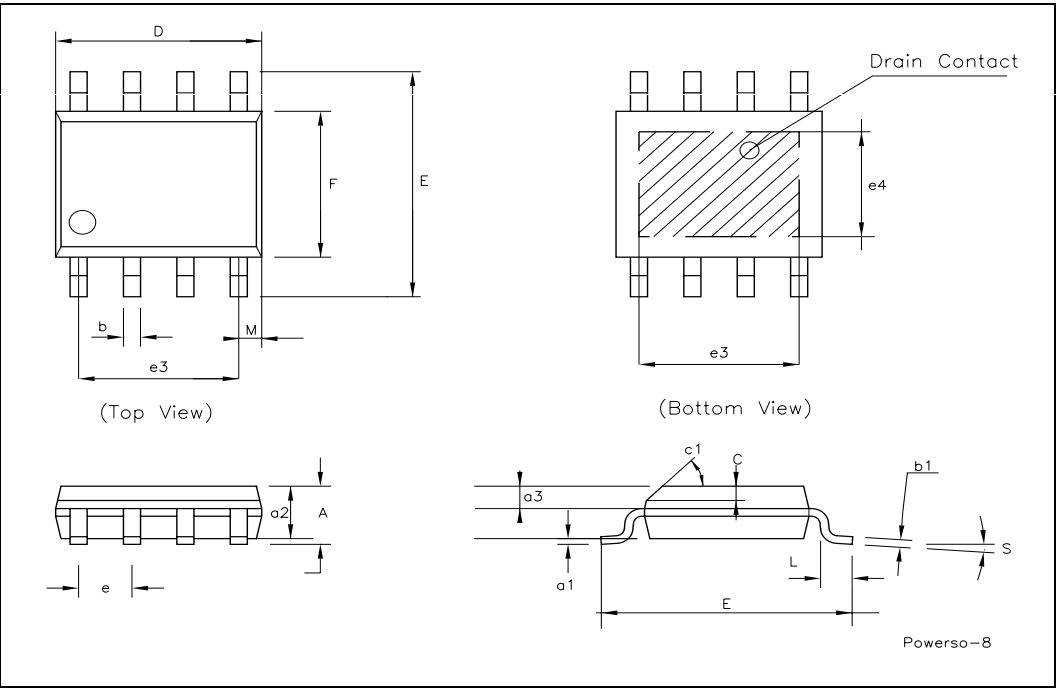
## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

Obsolete Product(s) - Obsolete Product(s)

PowerSO-8™ MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
C	0.25		0.5	0.010		0.019
c1	45° (typ.)					
D	4.8		5.0	0.188		0.196
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		3.81			0.150	
e4		2.79			0.110	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
M			0.6			0.023
S	8° (max.)					



## 5 Revision history

**Table 9. Document revision history**

Date	Revision	Changes
21-Jul-2004	1	Initial release.
24-May-2005	2	New value on <a href="#">Table 7</a>
23-Jun-2005	3	New Rg value on <a href="#">Table 7</a>
16-Nov-2005	4	Complete version
30-Mar-2006	5	New template
10-Dec-2007	6	Updated data on <a href="#">Table 4: Avalanche data</a>

**Please Read Carefully:**

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

**UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.**

**UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.**

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2007 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

[www.st.com](http://www.st.com)

# Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[STMicroelectronics:](#)

[STSJ50NH3LL](#)